

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

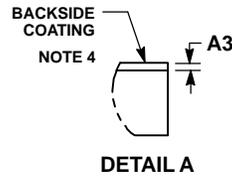
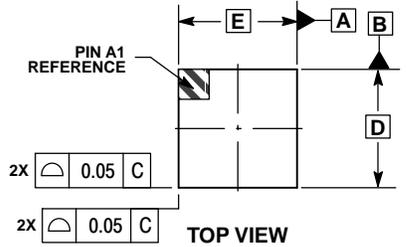
ON Semiconductor®



SCALE 4:1

WLCSP9, 1.31x1.31  
CASE 567HX  
ISSUE C

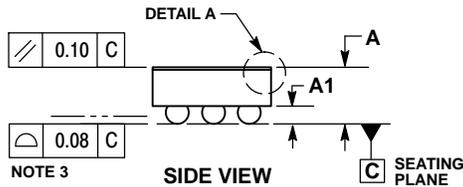
DATE 22 APR 2015



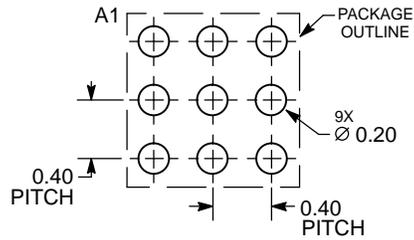
**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. BACKSIDE COATING IS OPTIONAL.

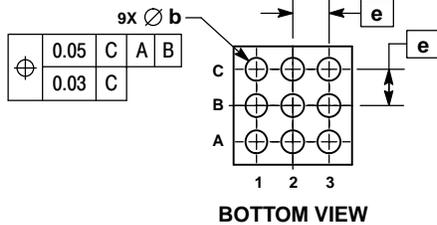
MILLIMETERS		
DIM	MIN	MAX
A	---	0.65
A1	0.16	0.26
A3	0.025 REF	
b	0.21	0.31
D	1.31 BSC	
E	1.31 BSC	
e	0.40 BSC	



**RECOMMENDED SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	WLCSP9, 1.31X1.31	<b>PAGE 1 OF 2</b>

